

METHOD FOR MAKING CIRCUIT ELEMENTS
FOR A Z-AXIS INTERCONNECT

ABSTRACT

5 Methods for producing circuit elements the resultant circuit elements, and
methods for making circuits therefrom are disclosed. A precursor circuit element
includes a first insulating layer with conductor thereon and an electrically conducting
member or bump, protruding from the conductor, that provide a shape to one surface
of the precursor circuit element. A second insulating layer, including an adhesive, is
10 placed onto the precursor circuit element and assumes the shape of the aforementioned
surface of the precursor circuit element. A portion of the insulating layer is removed
proximate the apex of the bump to expose at least a portion of the bump, for a
sufficient electrical connection with a subsequent circuit element, while maintaining a
sufficient amount of the insulating layer on the first initiating layer and bump to
15 facilitate the mechanical connection (bond) between this resultant circuit element and a
second circuit element, that may or may not have been produced by the method of the
present invention.